

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00729	3.23	0.10982
	Doped silicon	Silicon (Si)	7440-21-3	0.21826	96.77	3.29018
Subtotal				0.22555	100	3.4
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01595	10.0	0.24045
	Silver alloy	Silver (Ag)	7440-22-4	0.00319	2.0	0.04809
	Lead alloy	Lead (Pb)	7439-92-1	0.14037	88.0	2.11597
Subtotal				0.15951	100	2.40451
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.56972	100.0	8.58835
Subtotal				0.56972	100	8.58835
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00975	0.03	0.14694
	Pure metal layer	Zinc (Zn)	7440-66-6	0.0065	0.02	0.09796
	Pure metal layer	Tin (Sn)	7440-31-5	0.00975	0.03	0.14694
	Pure metal layer	Iron (Fe)	7439-89-6	0.03574	0.11	0.53877
	Pure metal layer	Copper (Cu)	7440-50-8	32.42907	99.81	488.8594
Subtotal				32.49081	100	489.79001
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.32173	100.0	4.85
Subtotal				0.32173	100	4.85
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.29862	8.0	79.8752
	Filler	Silica fused	60676-86-0	53.64849	81.0	808.7364
	Metal hydroxide	Metal hydroxide		0.46363	0.7	6.98908
	Carbon Black	Carbon black	1333-86-4	0.1987	0.3	2.99532
	Polymer	Epoxy resin system		6.62327	10.0	99.844
Subtotal				66.23271	100	998.44
Total				100.00003	100	1507.47287

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